

SOT1557-1

XFBGA121, plastic, extremely thin fine-pitch ball grid array;
121 bumps; 0.65 mm pitch; 8 mm x 8 mm x 0.5 mm body

31 March 2017

Package information

1. Package summary

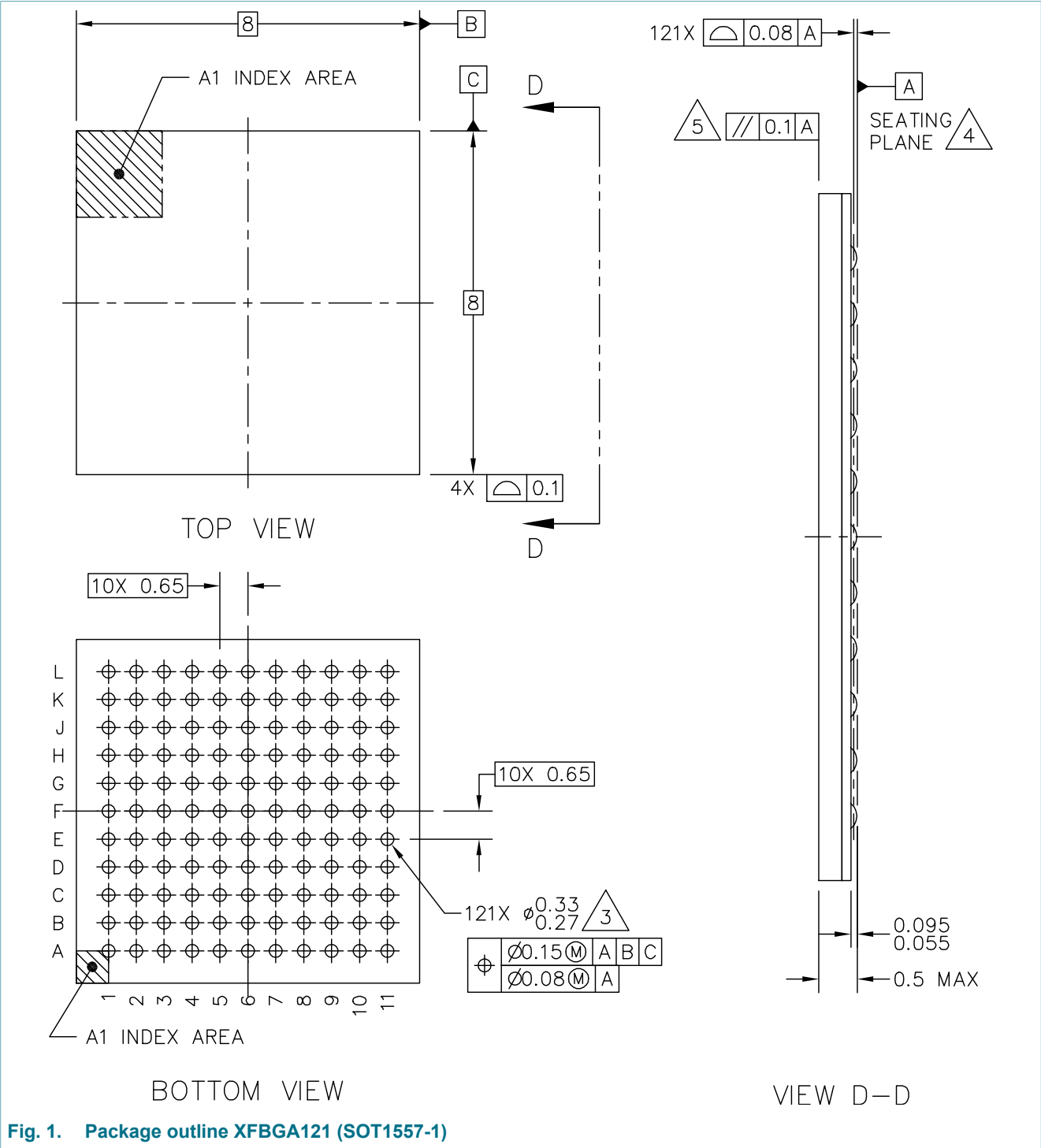
Terminal position code	B (bottom)
Package type descriptive code	XFBGA121
Package type industry code	XFBGA121
Package style descriptive code	XFBGA (extremely thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-3-2017
Manufacturer package code	98ASA00595D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	8	-	mm
E	package width		-	-	8	-	mm
A	seated height		-	-	0.5	-	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	121	-	



2. Package outline



XFBGA121, plastic, extremely thin fine-pitch ball grid array; 121 bumps; 0.65 mm pitch; 8 mm x 8 mm x 0.5 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

Fig. 2. Package outline note XFBGA121 (SOT1557-1)

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3. Legal information

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